

C. Huang et al.
U.S. Serial No. 09/823,176
Page 5

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AID

characterized by the provision of a warpage-preventive linkage structure, by which each substrate on the substrate strip is supported by means of no more than two tie bars, i.e., either by a two-point linkage structure or a one-point linkage structure, in contrast to the four-point linkage structure utilized by the prior art. During high-temperature fabrication steps when the substrate is subjected to thermal stresses, the substrate can freely expand toward the corners where no tie bars are provided; and consequently, it can be unwarped by the thermal stresses. This unwarped substrate allows the subsequently implanted ball grid array thereon to have high coplanarity.

IN THE CLAIMS

Please amend claims 9 and 14 as follows:

- Sul
B2
A11
9. (Amended) A substrate strip, which comprises:
- (a) a frame having a pair of parallel supporting bars including a first supporting bar and a second supporting bar; and
 - (b) at least one substrate supported on the supporting bars, the substrate being linked to the supporting bars by means of a two-point linkage structure consisting of just two tie bars linked to the supporting bars.

- Sul
B3
A12
14. (Amended) A substrate strip, which comprises:
- (a) a frame having a pair of parallel supporting bars including a first supporting bar and a second supporting bar; and
 - (b) at least one substrate supported on the supporting bars, the substrate being linked to the supporting bars by means of a one-point linkage structure consisting of just one tie bar linked to one of the two supporting bars.

REMARKS

Claims 1-16 are pending in the application. Claims 9 and 14 have been amended to overcome the claim objections to the term "at least one substrates," which has been changed to "at least one substrate." The specification has been amended to correct inadvertent errors.